

IN THE CLAIMS

Please amend the claims as follows:

Claim 1. (Original) A thermoelectric module comprising:

a case;

a heat-radiation side insulating substrate;

a heat-absorption side insulating substrate;

a first soldering layer formed of a first soldering agent at a position to connect the heat-radiation side insulating substrate and the case;

a plurality of P-type and N-type semiconductor chips interposed between the heat-radiation side insulating substrate and the heat-absorption side insulating substrate, the plurality of P-type and N-type semiconductor chips being arranged alternately to be connected in a series; and

a second soldering layer formed of a second soldering agent at a position to connect the heat-radiation side insulating substrate and one end of each of the plural P-type and N-type semiconductor chips, the second soldering layer also connecting the heat-absorption side insulating substrate and the other end of each of the plural P-type and N-type semiconductor chips, the second soldering agent being identical with the first soldering agent in raw material.

Claim 2. (Currently Amended) A method of producing a thermoelectric module comprising the steps of:

connecting a case and a heat-radiation side insulating substrate with a first soldering agent to form a first soldering layer between the case and the heat-radiation side insulating substrate; and

connecting the heat-radiation side insulating substrate and a heat-absorption side insulating substrate to ~~and~~ one end and the other end, respectively, of each of a plurality of P-type and N-type semiconductor chips, with a second soldering agent which is identical with the first soldering agent in raw material.

Claim 3. (Currently Amended) A thermoelectric module as set forth in Claim 1, wherein the first soldering agent and the second soldering agent are selected from the group consisting of 95Sn5Sb, 91Sn9Zn, 96.5Sn3.5Ag, 97.5Sn2.5Ag, 100Sn, 65Sn25Ag10Sb, 99Sn1Sb, 90In10Ag, 97Sn3Sb, 95Sn5Ag, 93Sn7Sb, 80Au20Sn, 90Sn10Ag, and 97Sn3Cu.

4. (Currently Amended) A method of producing a thermoelectric module as set forth in Claim 2, wherein the first soldering agent and the second soldering agent are selected from the group consisting of 95Sn5Sb, 91Sn9Zn, 96.5Sn3.5Ag, 97.5Sn2.5Ag, 100Sn, 65Sn25Ag10Sb, 99Sn1Sb, 90In10Ag, 97Sn3Sb, 95Sn5Ag, 93Sn7Sb, 80Au20Sn, 90Sn10Ag, and 97Sn3Cu.